

IBIS-AMI Concern for PAM4 Simulation

Asian IBIS Summit
Tokyo, Japan
November 16, 2015

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Outline

- 56 Gbps coming soon
- How to realize 56 Gbps
- What is PAM4
- How to simulate PAM4
- IBIS-AMI
- Concern for IBIS-AMI

56 Gbps Coming Soon

- 400G Ethernet
- Release Schedule: 2017
- 50 Gbps x 8 Line

Name	Speed	Date Initial Standard Ratified
10Mb/s Ethernet	10 Mb/s	1983
100Mb/s Ethernet	100Mb/s	1995
Gigabit Ethernet	1 Gb/s	1998
10 Gigabit Ethernet	10 Gb/s	2002
25 Gigabit Ethernet	25Gb/s	2016 (est)*
40 Gigabit Ethernet	40 Gb/s	2010
100 Gigabit Ethernet	100 Gb/s	2010
400 Gigabit Ethernet	400 Gb/s	2017 (est.)**

(<http://www.ethernetalliance.org/subcommittees/roadmap-subcommittee/>)

OFI (Optical Internetworking Forum)

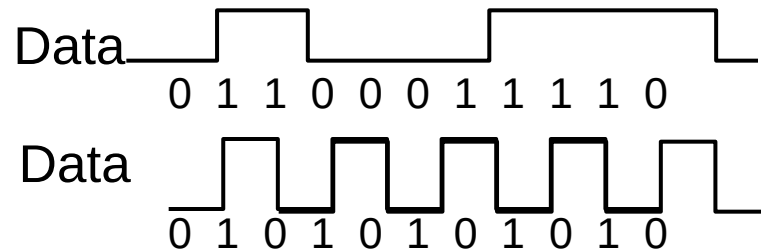
- CEI-56G

- CIE-56G-USR: 2.5D/3D Chip-Chip > 1 cm
- CIE-56G-XSR: Chip-Near Optics > 5 cm
- CIE-56G-VSR: Chip-Module > 10 cm
- CIE-56G-MR: Chip-Chip, Chip-Module > 50 cm/1 connector
- CIE-56G-LR: Chip-Backplane-Chip >100 cm/2 connectors

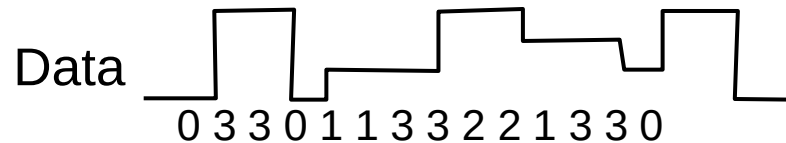
- 400G/200G: 56G x 8/4

How to Reach 56 Gbps

- NRZ (Embedded Clock) 28 GHz/56Gbps

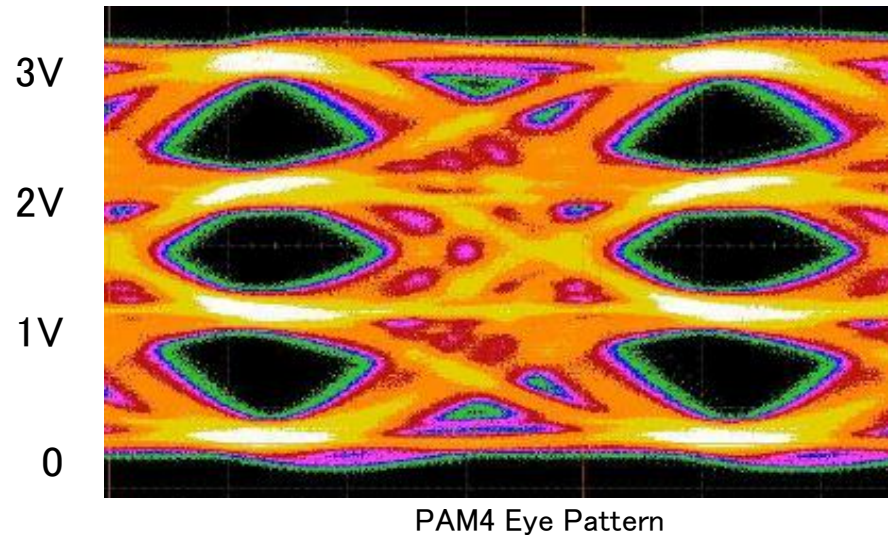
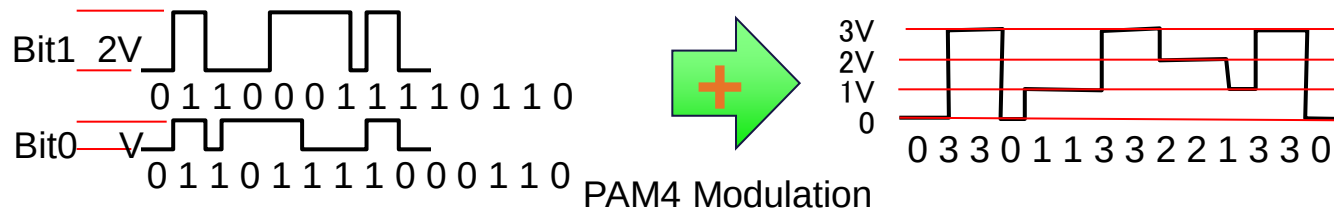


- PAM4 (4 Values Transmission) 14GHz/56Gbps



What is PAM4

- 4 Level Transmission



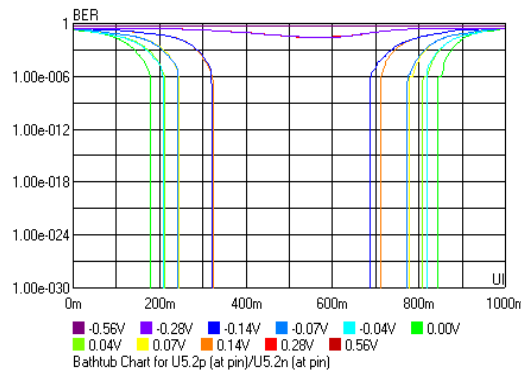
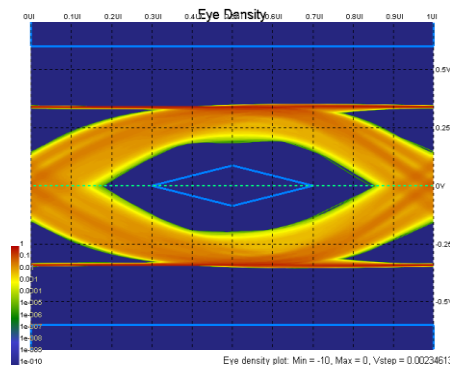
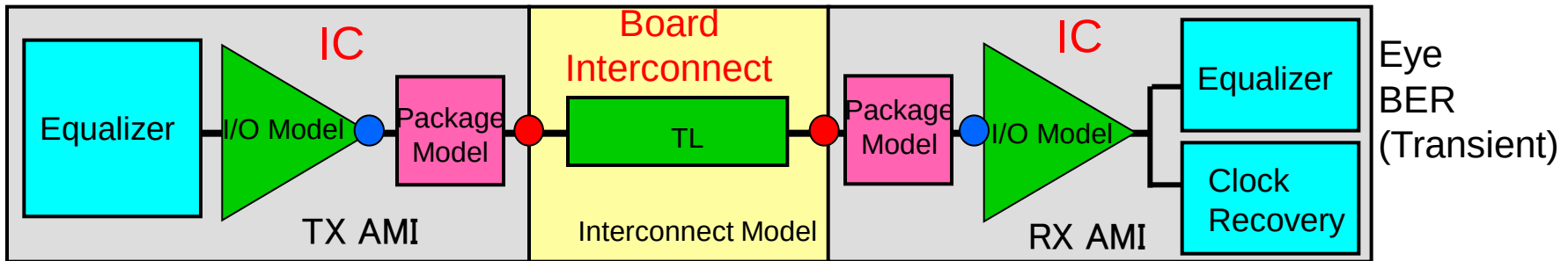
(E.Frlan, C.YeLiu, M.PengLi “Signal Integrity Challenges & Solutions for Next-Generation CEI-56G “Chip-to-Module” & “Chip-to-Chip” Interface, DesignCon 2015)

How to Simulate PAM4

- S-parameter: Interconnect/Connector
 - Insertion loss
- Input: Ideal input
- Want to use actual driver model for simulation!
 - IBIS-AMI
- BER
 - 10^{-18} BER have 1 error/hr.

IBIS-AMI

- **Only One Solution** of High-Speed Serial Link Simulation
- Analog Circuit (Active/Passive Equalizer)
- Fastest Simulation (BER Analysis)
- Random Jitter Effect Analysis



IBIS-AMI is Based on Linear Model

- Model Description
 - IO Model
 - AMI Model

```
[Model]
[**Range]
[Algorithmic Model]
    Executable
[End Algorithmic Model]
[I-V]
[Slew Rate]
```

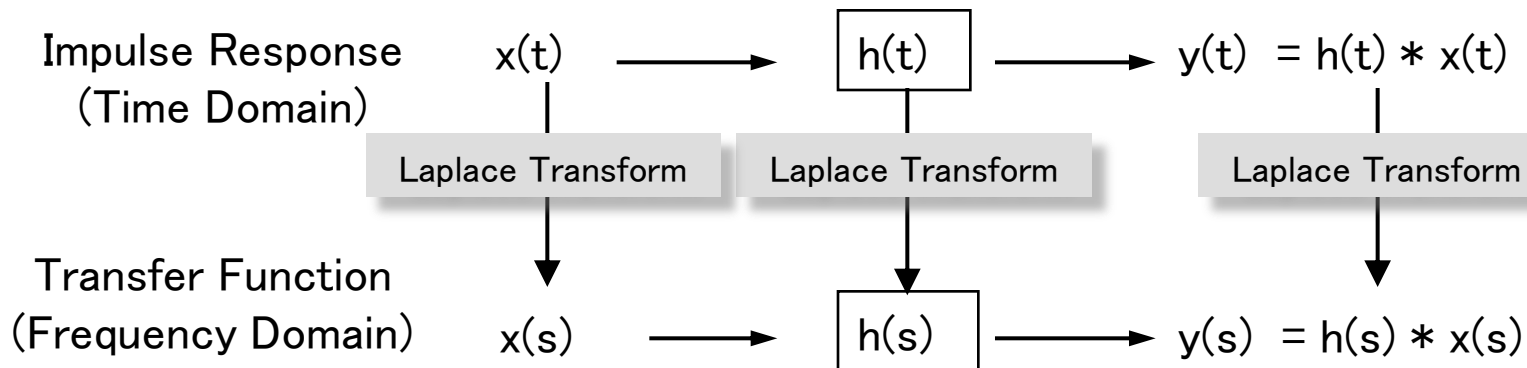
```
[Model] xxxx
Model_type Output
C_comp 800f 750f 850f
Cref = 0
[Model Spec]
Vmeas .157 .15 .165
Vref .157 .15 .165
[Temperature Range] 25 100 0
[Voltage Range] .314 .299 .329
[Algorithmic Model]
Executable Windows_VisualStudio7.1.3088_32 xx_gtp_ami_tx.dll xx_gtp_ami_tx_1.ami
Executable Linux_gcc3.2.3_32 xx_gtp_ami_tx.linux.so xx_gtp_ami_tx_1.ami
[End Algorithmic Model]
[Pulldown]
-2.500 -4.95638E-02 -5.02816E-02 -4.88759E-02
0.000 +0.00000E+00 +0.00000E+00 +0.00000E+00
2.500 +4.95638E-02 +5.02816E-02 +4.88759E-02
[Pullup]
-2.500 +4.95638E-02 +5.02816E-02 +4.88759E-02
0.000 +0.00000E+00 +0.00000E+00 +0.00000E+00
2.500 -4.95638E-02 -5.02816E-02 -4.88759E-02
[Ramp]
dV/dt_r .094/60f .09/60f .098/60f
dV/dt_f .094/60f .09/60f .098/60f
|
```

IBIS-AMI is based on Impulse Response

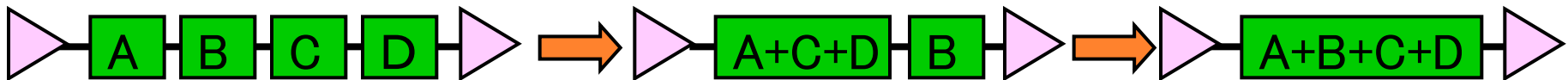
- Impulse Response
 - Output when Input the Impulse (Function)



- “Impulse Response” is Laplace Transformed “Transfer Function”

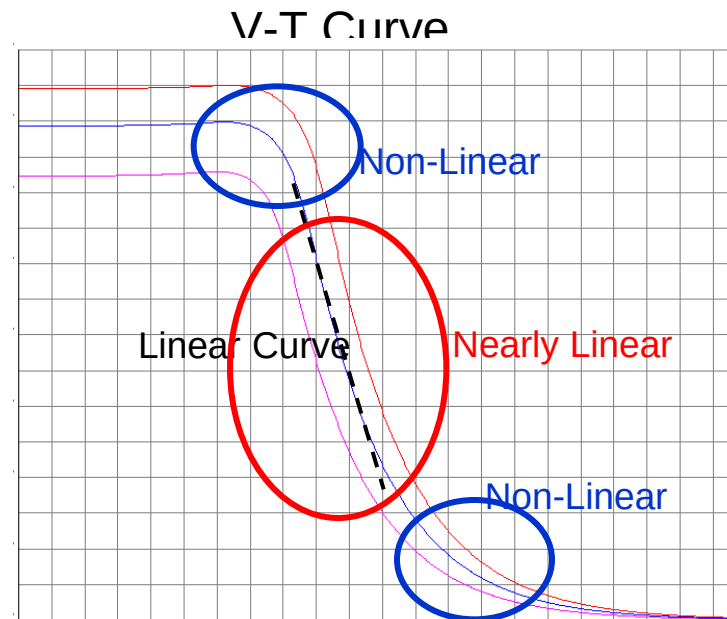


- Precondition: **LTI** (Linear and Time Invariant)



Real Driver is **Not** Linear

- Approximation to Linear
- Can Apply LTI Condition?

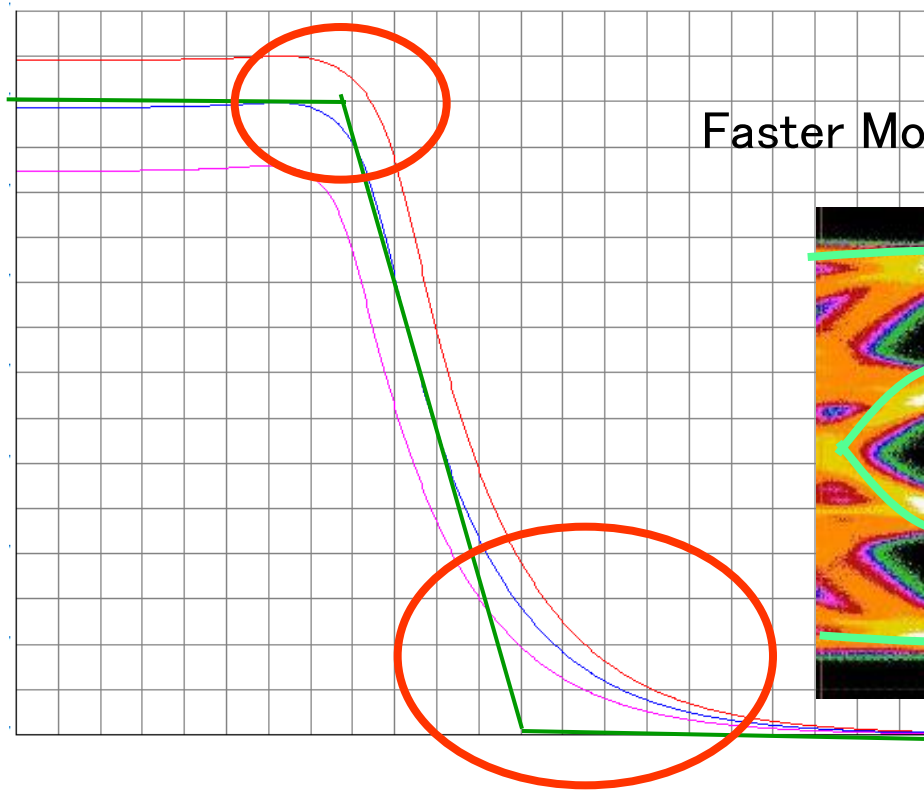
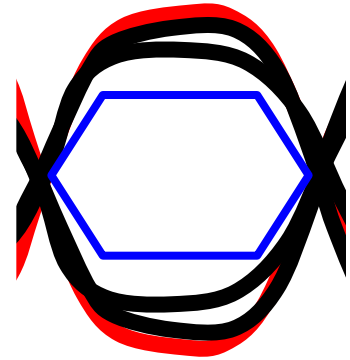


Simulation Accuracy using AMI Model?

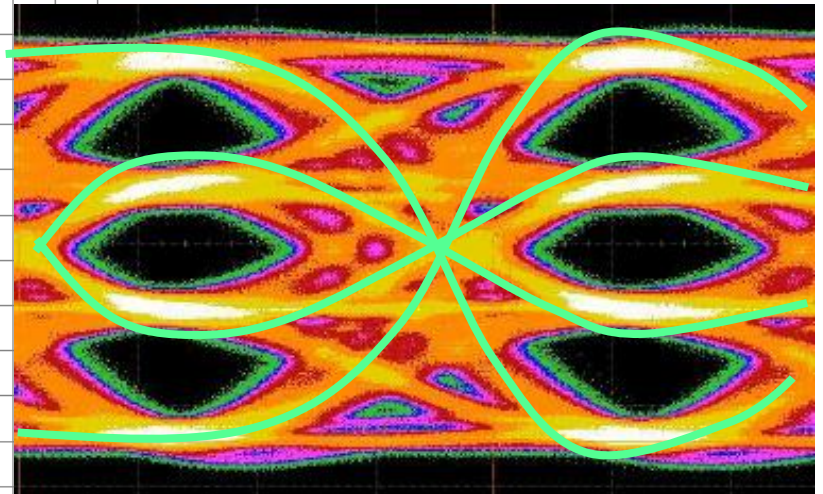
➔ Checking Simulation Accuracy by IBIS Open Forum, Vendors and Users

Linear Model Makes V-Level Higher

- Linear Model is faster than actual
- Faster Model makes ringing bigger



Faster Model is not critical case for NRZ



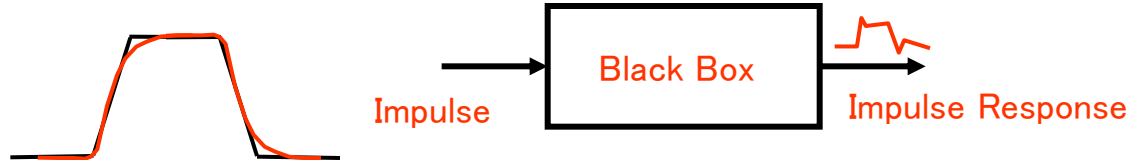
for PAM4?

KEI Systems

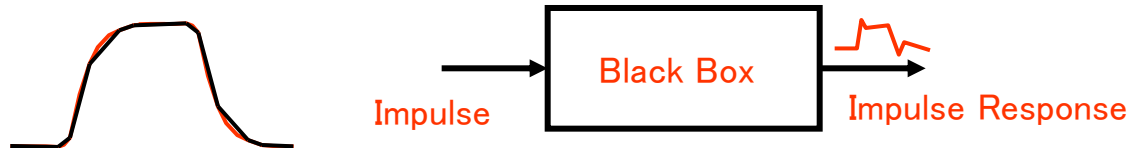
Use More Accurate Impulse Response

- Use Stepped Linear Model

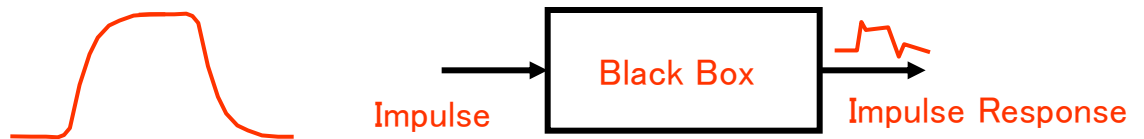
Linear Model



Divided Linear Model



Non-Linear Model



Corner Analysis

- IBIS-AMI model: Only one case
- Critical NRZ Eye Analysis: Slow Model ?
- Critical PAM4 Eye Analysis ?
 - Which is Critical, Fast/Typ/Slow Model ?

Conclusion

- PAM4 will be important
- How to Simulate PAM4/PAMn ?
- IBIS-AMI is best choice for now.
- There are some worries for IBIS-AMI to simulate PAM4
 - Linear Model
 - Corner Simulation

Reference

- E.Frlan, C.YeLiu, M.PengLi “Signal Integrity Challenges & Solutions for Next-Generation CEI-56G “Chip-to-Module” & “Chip-to-Chip” Interface”, DesignCon 2015
- Shinichi Maeda, KEI Systems “IBIS-AMI Model (Algorithmic Model Interface) ~Theory & Structure~” , Asian IBIS Summit, Japan 2013
- Motoaki Mtsumura, FUJITSU Semiconductor Ltd., “The Application of Simulation Kit Using USB 3.0 IBIS-AMI Model” ” , Asian IBIS Summit, Japan 2012
- Ryan Cotts, Netlogic and others “AMI Modeling Methodology and Measurment Correlation of a 6.25Gb/s Link” IBIS Summit DAC, 2011